

300mm Fully-Automatic BG Tape Remover

RAD-3010F/12



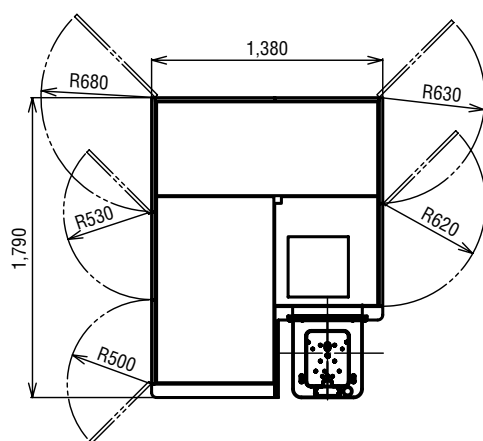
Outline

- Fully-automatic BG Tape remover for single wafer.
- After alignment, UV is irradiated when necessary, and back grinding tape is removed by attaching heat seal on the periphery of the wafer, fixed with heater.

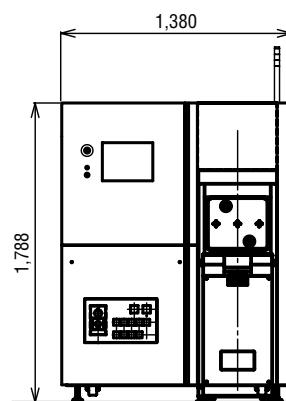
Options ·Host Communication Function (Communication Format :
Conforms to SECS-I and HSMS/Software : Conforms to GEM)
·Barcode Reader for Selecting Recipes

Suitable Tapes ·BG Tape : Adwill E series, P series

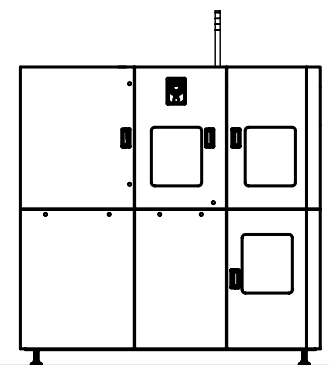
External View



Top View



Front View



Left Side View

Unit:mm

Facility

| | | |
|----------------------|-----------------|-----------------------------------|
| Power Supply | Voltage | : AC200-230V ±10% (AC190-253V) |
| | Frequency | : 50/60Hz |
| | Phase | : single phase |
| Air Supply | Capacity | : 5.0kW |
| | Air pressure | : 0.5-0.8MPa |
| Vacuum Supply | Air consumption | : >150L/min (ANR) |
| | Vacuum pressure | : >-80kPa |

Applicable Wafer Size 200mm, 300mm

Size Width : 1,380mm
Depth : 1,790mm
Height : 1,788mm
(excluding the signal tower)

Weight 1,100kg

UPH 65wafers/hour

The above processing capacity is based on following conditions:

Wafer : 300mm diameter non-polished mirror wafer
Back grinding tape : E-6152 from LINTEC



LINTEC Corporation *Linking your dreams*

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